

ABSTRACT OF THE DISCLOSURE

The vacuum processing device comprises vacuum processing chambers 30a and 30b for performing predetermined treatments to a wafer being transferred to a predetermined position within the chamber, an atmospheric transfer equipment 7 for transferring a wafer in atmospheric air to a vacuum transfer equipment 10, a vacuum transfer equipment 10 disposed within a vacuum transfer chamber 2 connecting the atmospheric air and said vacuum processing chambers for transferring the wafer received from said atmospheric transfer equipment to said predetermined position within said vacuum processing chamber, and wafer position sensors 11a, 11b, 11c and 11d disposed near the ingress path leading into said processing chambers for detecting the displacement of said wafers being transferred.